



Tentative Specification
Preliminary Specification
Approval Specification

# MODEL NO.: G170ECE SUFFIX: LE2

Customer: ALL					
APPROVED BY	SIGNATURE				
Name / Title Note					
Please return 1 copy for you signature and comments.	r confirmation with your				

Approved By	Checked By	Prepared By
林秋森	吳承旻	王啟瑜

Version 2.0 10 May 2024 1 / 38



# **CONTENTS**

1.1 OVERVIEW       5         1.2 FEATURE       5         1.3 APPLICATION       5         1.4 GENERAL SPECIFICATIONS       5         1.5 MECHANICAL SPECIFICATIONS       5         2. ABSOLUTE MAXIMUM RATINGS       6         2.1 ABSOLUTE RATINGS OF ENVIRONMENT       6         2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. TFT LCD MODULE       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5.1 TFT LCD MODULE       11         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22	1. GENERAL DESCRIPTION	5
1.3 APPLICATION       5         1.4 GENERAL SPECIFICATIONS       5         1.5 MECHANICAL SPECIFICATIONS       5         2. ABSOLUTE MAXIMUM RATINGS       6         2.1 ABSOLUTE RATINGS OF ENVIRONMENT       6         2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5.1 NPUT TERMINAL PIN ASSIGNMENT       12         5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         8. RELIABILITY TEST CRITERIA       22         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25 <td< td=""><td>1.1 OVERVIEW</td><td>5</td></td<>	1.1 OVERVIEW	5
1.4 GENERAL SPECIFICATIONS	1.2 FEATURE	5
1.5 MECHANICAL SPECIFICATIONS       5         2. ABSOLUTE MAXIMUM RATINGS       6         2.1 ABSOLUTE RATINGS OF ENVIRONMENT       6         2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4 BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       12         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7.0 PTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AN	1.3 APPLICATION	5
2. ABSOLUTE MAXIMUM RATINGS       6         2.1 ABSOLUTE RATINGS OF ENVIRONMENT       6         2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       18         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODUL	1.4 GENERAL SPECIFICATIONS	5
2.1 ABSOLUTE RATINGS OF ENVIRONMENT       6         2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LA	1.5 MECHANICAL SPECIFICATIONS	5
2.2 ELECTRICAL ABSOLUTE RATINGS       7         2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECA	2. ABSOLUTE MAXIMUM RATINGS	6
2.2.1 TFT LCD MODULE       7         2.2.2 BACKLIGHT UNIT       7         3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS	2.1 ABSOLUTE RATINGS OF ENVIRONMENT	6
2.2.2 BACKLIGHT UNIT	2.2 ELECTRICAL ABSOLUTE RATINGS	7
3. ELECTRICAL CHARACTERISTICS       8         3.1 TFT LCD MODULE       8         3.2 BACKLIGHT UNIT       9         4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	2.2.1 TFT LCD MODULE	7
3.1 TFT LCD MODULE 8 3.2 BACKLIGHT UNIT 9 4. BLOCK DIAGRAM 11 4.1 TFT LCD MODULE 11 5. INPUT TERMINAL PIN ASSIGNMENT 12 5.1 TFT LCD MODULE 12 5.2 BACKLIGHT UNIT (CONVERTER CONNECTOR PIN) 13 5.3 COLOR DATA INPUT ASSIGNMENT 14 6. INTERFACE TIMING 15 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 15 6.2 POWER ON/OFF SEQUENCE 17 6.3 SCANNING DIRECTION 18 7. OPTICAL CHARACTERISTICS 19 7.1 TEST CONDITIONS 19 7.2 OPTICAL SPECIFICATIONS 19 8. RELIABILITY TEST CRITERIA 22 9. PACKAGING 23 9.1 PACKING METHOD 23 9.2 PACKING METHOD 24 10. DEFINITION OF LABELS 25 10.1 INX MODULE LABEL 25 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 26 11.2 STORAGE PRECAUTIONS 26 11.2 STORAGE PRECAUTIONS 26 11.2 STORAGE PRECAUTIONS 26	2.2.2 BACKLIGHT UNIT	7
3.2 BACKLIGHT UNIT	3. ELECTRICAL CHARACTERISTICS	8
4. BLOCK DIAGRAM       11         4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING METHOD       23         9.2 PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	3.1 TFT LCD MODULE	8
4.1 TFT LCD MODULE       11         5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	3.2 BACKLIGHT UNIT	9
5. INPUT TERMINAL PIN ASSIGNMENT       12         5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	4. BLOCK DIAGRAM	11
5.1 TFT LCD MODULE       12         5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	4.1 TFT LCD MODULE	11
5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)       13         5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26          11.2 STORAGE PRECAUTIONS       26	5. INPUT TERMINAL PIN ASSIGNMENT	12
5.3 COLOR DATA INPUT ASSIGNMENT       14         6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
6. INTERFACE TIMING       15         6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
6.1 INPUT SIGNAL TIMING SPECIFICATIONS       15         6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	5.3 COLOR DATA INPUT ASSIGNMENT	14
6.2 POWER ON/OFF SEQUENCE       17         6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
6.3 SCANNING DIRECTION       18         7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
7. OPTICAL CHARACTERISTICS       19         7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
7.1 TEST CONDITIONS       19         7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
7.2 OPTICAL SPECIFICATIONS       19         8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	7. OPTICAL CHARACTERISTICS	19
8. RELIABILITY TEST CRITERIA       22         9. PACKAGING       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	7.1 TEST CONDITIONS	19
9. PACKAGING.       23         9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
9.1 PACKING SPECIFICATIONS       23         9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	8. RELIABILITY TEST CRITERIA	22
9.2 PACKING METHOD       23         9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
9.3 UN-PACKING METHOD       24         10. DEFINITION OF LABELS       25         10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26		
10. DEFINITION OF LABELS	9.2 PACKING METHOD	23
10.1 INX MODULE LABEL       25         11. PRECAUTIONS       26         11.1 ASSEMBLY AND HANDLING PRECAUTIONS       26         11.2 STORAGE PRECAUTIONS       26	9.3 UN-PACKING METHOD	24
11. PRECAUTIONS2611.1 ASSEMBLY AND HANDLING PRECAUTIONS2611.2 STORAGE PRECAUTIONS26	10. DEFINITION OF LABELS	25
11.1 ASSEMBLY AND HANDLING PRECAUTIONS26 11.2 STORAGE PRECAUTIONS26		
11.2 STORAGE PRECAUTIONS26	11. PRECAUTIONS	26



#1 /A37 6 -6	
11.3 OTHER PRECAUTIONS	27
12. MECHANICAL CHARACTERISTICS	28
Appendix. SYSTEM COVER DESIGN NOTICE	

Version 2.0 10 May 2024 3 / 38



# **REVISION HISTORY**

Version	Date	Page	Description
Ver 2.0	10 May 2024	All	Approval Specification was first issued

Version 2.0 10 May 2024 4 / 38



## 1. GENERAL DESCRIPTION

#### 1.1 OVERVIEW

INNOLUX

群創光電

G170ECE-LE2 is a 17.0" TFT Liquid Crystal Display IA module with LED Backlight units and 30 pins LVDS interface. This module supports 1280 X 1024 SXGA mode and can display 16.7M colors.

The PSWG is to establish a set of displays with standard mechanical dimensions and select electrical interface requirements for an industry standard 17.0" SXGA LCD panel. The converter module for LED backlight is built-in.

### **1.2 FEATURE**

- SXGA (1280 x 1024 pixels) resolution
- DE (Data Enable) only mode
- LVDS Interface with 2pixel/clock
- PSWG (Panel Standardization Working Group)
- RoHS compliance

#### 1.3 APPLICATION

- -TFT LCD Monitor
- Factory Application

#### 1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	337.92(H) x 270.336(V) (17.0" diagonal)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	1280 x R.G.B x 1024	pixel	-
Pixel Pitch	0.264(H) x 0.264(W)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	16.7M	color	-
Display Mode	Normally Black	-	-
Surface Treatment	Hard Coating (3H), Anti-Glare	-	-
Module Power Consumption	13.68W (Cell:1.68W + CNV:12W)	W	Тур.

### 1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Тур.	Max.	Unit	Note
	Horizontal(H)	358.0	358.5	359	mm	
Module Size	Vertical(V)	296.0	296.5	297.0	mm	(1)
	Depth(D)	-	21.44	22.44	mm	
Dozel Area	Horizontal	341.62	341.92	342.22	mm	-
Bezel Area	Vertical	274.04	274.34	274.64	mm	
Active Area	Horizontal	-	337.92	-	mm	
Active Area	Vertical	-	270.336	-	mm	
Weight		-	1340	1400	g	

Note (1)Please refer to the attached drawings for more information of front and back outline dimensions.

Version 2.0 10 May 2024 5 / 38



### 2. ABSOLUTE MAXIMUM RATINGS

### 2.1 ABSOLUTE RATINGS OF ENVIRONMENT

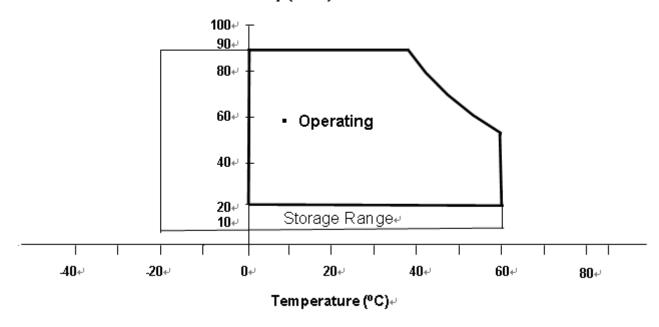
lto.m	Cumbal	Va	lue	Lloit	Note	
Item	Symbol	Min.	Max.	Unit	Note	
Operating Ambient Temperature	TOP	0	+60	$^{\circ}\!\mathbb{C}$	(4)(2)	
Storage Temperature	Tst	-20	+60	$^{\circ}\!\mathbb{C}$	(1)(2)	

Note (1)

- (a) 90 %RH Max.
- (b) Wet-bulb temperature should be 39 °C Max.
- (c) No condensation.

Note (2) Panel surface temperature should be  $0^{\circ}$ C min. and  $60^{\circ}$ C max under Vcc=5.0V, fr =60Hz, typical LED string current,  $25^{\circ}$ C ambient temperature, and no humidity control . Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than  $60^{\circ}$ C.(Panel surface temperature.)

### Relative Humidity (%RH)₽



Version 2.0 10 May 2024 6 / 38



### 2.2 ELECTRICAL ABSOLUTE RATINGS

### 2.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note	
item	Symbol	Min.	Max.	Offic	note	
Power Supply Voltage VCC		-0.3	6	V	(1)	
Logic Input Voltage	Vin	-0.3	3.6	V	(1)	

### 2.2.2 BACKLIGHT UNIT

ltom	Symbol	Va	lue	Unit	Noto	
Item	Symbol	Min.	Max.	Offic	Note	
Converter Voltage	Vi	-0.3	18	V	(1), (2)	
Enable Voltage	EN		5.5	V		
Backlight Adjust	Dimming		5.5	V		

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for LED (Refer to 3.2 for further information).



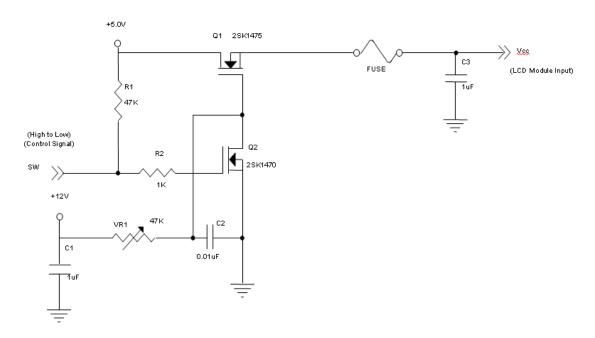
### 3. ELECTRICAL CHARACTERISTICS

### 3.1 TFT LCD MODULE

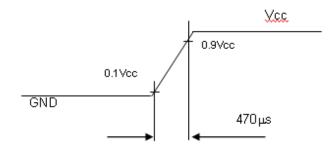
Parameter	Cumbal	Value			Unit	Note	
Parameter	Symbol	Min.	Тур.	Max.	Offit	Note	
Power Supply Vo	ltage	Vcc	4.5	5.0	5.5	V	-
Ripple Voltage	е	$V_{RP}$	1	ı	300	mVp-p	-
Inrush Current		INRUSH	ı	ı	2.0	Α	(2)
Dower Supply Current	White	laa		320	380	mA	(3)a
Power Supply Current	Black	lcc	-	335	395	mA	(3)b
LVDS differential inpu	it voltage	$V_{id}$	200	ı	600	mV	-
LVDS common input voltage		Vic	1.0	1.2	1.4	V	-
Differential Input Voltage for	"H" Level	ViH	-	-	100	mV	-
LVDS Receiver Threshold	"L" Level	VIL	-100	-	-	mV	-
Terminating Res	istor	R⊤	-	100	-	Ohm	-

Note (1) The module should be always operated within above ranges.

Note (2)Measurement Conditions:



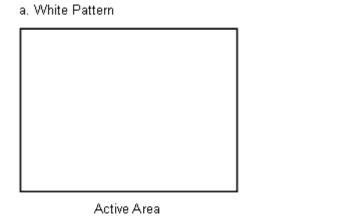
## Vcc rising time is 470µs



Version 2.0 10 May 2024 8 / 38



Note (3)The specified power supply current is under the conditions at Vcc = 5.0 V, Ta = 25  $\pm$  2  $^{\circ}$ C, DC Current and f<sub>v</sub> = 60 Hz, whereas a power dissipation check pattern below is displayed.



b. Black Pattern



Active Area

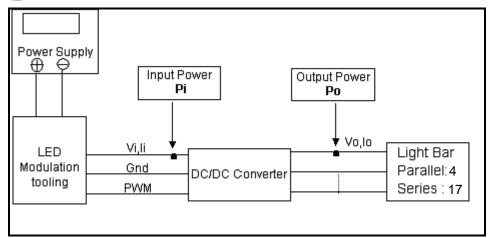
## 3.2 BACKLIGHT UNIT

Davam	oto "	Cumabal		Value		l lait	Note
Param	eter	Symbol	Min.	Тур.	Max.	Unit	Note
Converter Inp	ut Voltage	Vi	10.8	12.0	13.2	V <sub>DC</sub>	(Duty 100%)
Converter Input F	Ripple Voltage	$V_{iRP}$	-	-	500	mV	
Converter Inp	ut Current	li	0.8	1	1.2	ADC	@ Vi = 12V (Duty 100%)
Converter Inru	lirush	-	-	5.0	А	@ Vi rising time=10ms (Vi=12V)	
Input Power Co	onsumption	Pi	9.6	12	14.4	W	(1)
EN Control Level	Backlight on	ENLED	2.0	3.3	5.0	V	
LIN COILLOI LEVEI	Backlight off	(BLON)	0	-	0.3	V	
PWM Control Level	PWM High Level	Dimming	2.0	-	5.0	V	
r www.control Level	PWM Low Level	(E_PWM)	0	-	0.15	V	
PWN Noise	Range	VNoise	-	-	0.1	V	
PWM Control	Frequency	f <sub>PWM</sub>	190	200	20k	Hz	(3)
DIAMA Dimming Co		5	-	100	%	(3), @ 190Hz <f<sub>PWM&lt;1kHz</f<sub>	
PWM Dimming Co	niioi buly Ratio	-	20	-	100	%	(3), @ 1kHz≦f <sub>PWM</sub> <20kHz
LED Life	Time	L <sub>LED</sub>	50,000		-	Hrs	(2)

Note (1)LED current is measured by utilizing a high frequency current meter as shown below:

Version 2.0 10 May 2024 9 / 38





- Note (2) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at Ta = 25 ±2 °C and Duty 100% until the brightness becomes ≤ 50% of its original value.

  Operating LED at high temperature condition will reduce life time and lead to color shift.
- Note (3) At 190 ~1kHz PWM control frequency, duty ratio range is restricted from 5% to 100%.

  1K ~20kHz PWM control frequency, duty ratio range is restricted from 20% to 100%.

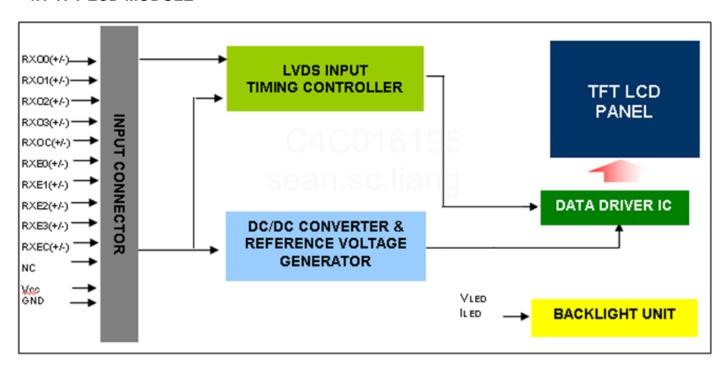
  If PWM control frequency is applied in the range from 1KHz to 20KHZ, The "non-linear" phenomenon on the Backlight Unit may be found. So It's a suggestion that PWM control frequency should be less than 1KHz.

Version 2.0 10 May 2024 10 / 38



### 4. BLOCK DIAGRAM

### 4.1 TFT LCD MODULE





### 5. INPUT TERMINAL PIN ASSIGNMENT

### 5.1 TFT LCD MODULE

Pin	Name	Description
1	RXO0-	Negative LVDS differential data input. Channel O0 (odd)
2	RXO0+	Positive LVDS differential data input. Channel O0 (odd)
3	RXO1-	Negative LVDS differential data input. Channel O1 (odd)
4	RXO1+	Positive LVDS differential data input. Channel O1 (odd)
5	RXO2-	Negative LVDS differential data input. Channel O2 (odd)
6	RXO2+	Positive LVDS differential data input. Channel O2 (odd)
7	GND	GND
8	RXOC-	Negative LVDS differential clock input. (odd)
9	RXOC+	Positive LVDS differential clock input. (odd)
10	RXO3-	Negative LVDS differential data input. Channel O3(odd)
11	RXO3+	Positive LVDS differential data input. Channel O3 (odd)
12	RXE0-	Negative LVDS differential data input. Channel E0 (even)
13	RXE0+	Positive LVDS differential data input. Channel E0 (even)
14	GND	GND
15	RXE1-	Negative LVDS differential data input. Channel E1 (even)
16	RXE1+	Positive LVDS differential data input. Channel E1 (even)
17	GND	GND
18	RXE2-	Negative LVDS differential data input. Channel E2 (even)
19	RXE2+	Positive LVDS differential data input. Channel E2 (even)
20	RXEC-	Negative LVDS differential clock input. (even)
21	RXEC+	Positive LVDS differential clock input. (even)
22	RXE3-	Negative LVDS differential data input. Channel E3(even)
23	RXE3+	Positive LVDS differential data input. Channel E3 (even)
24	GND	GND
25	NC	For LCD internal use only, Do not connect
26	NC	For LCD internal use only, Do not connect
27	NC	For LCD internal use only, Do not connect
28	Vcc	+5.0V power supply
29	Vcc	+5.0V power supply
30	Vcc	+5.0V power supply

Note (1)Connector Part No.: P-TWO 187098-30091 or FCN WF13-428-3033 or equivalent.

Note (2) User's connector Part No: JAE FI-X30H or JAE FI-X30HL or equivalent.

Note (3) The first pixel is odd.

Note (4) Input signal of even and odd clock should be the same timing.

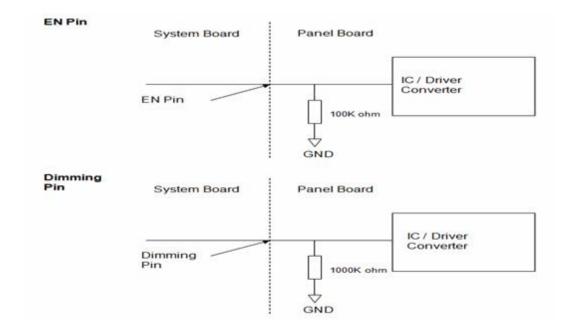


## **5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)**

Pin	Symbol	Description	Remark
1	Vi	Converter input voltage	12V
2	Vi	Converter input voltage	12V
3	Vi	Converter input voltage	12V
4	Vi	Converter input voltage	12V
5	V <sub>GND</sub>	Converter ground	Ground
6	$V_{GND}$	Converter ground	Ground
7	$V_{GND}$	Converter ground	Ground
8	$V_{GND}$	Converter ground	Ground
9	EN	Enable pin	3.3V
10	Dimming	Backlight Adjust	PWM Dimming (Hi: 3.3V <sub>DC</sub> , Lo: 0V <sub>DC</sub> )

Note (1)Connector Part No.: CviLux Cl0110M1HR0-NH or equivalent.

Note (2)User's connector Part No.: CviLux CI0110S0000 or equivalent.



Version 2.0 10 May 2024 13 / 38



### **5.3 COLOR DATA INPUT ASSIGNMENT**

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

												D	ata	_	nal										
	Color				Re									een							BI				
	<u> </u>	R7	R6	R5	R4	_	R2	R1	R0	G7	G6	G5	G4	G3	G2		G0	B7	B6	B5	B4	В3	B2	B1	B0
	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Basic	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
Colors	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Cross	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Red	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
Gray	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Green	Green(253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
Green	Green(254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green(255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
Gray	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Blue	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
Diue	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

Note (1)0: Low Level Voltage, 1: High Level Voltage



#### 6. INTERFACE TIMING

### **6.1 INPUT SIGNAL TIMING SPECIFICATIONS**

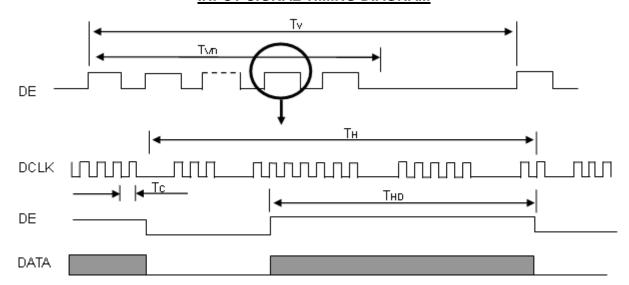
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Тур.	Max.	Unit	Note
	Frequency	Fc	45	54	69.3	MHz	-
	Period	Tc	14.43	18.52	22.22	ns	-
	Input cycle to cycle jitter	T <sub>rcl</sub>	-0.02*TC		0.02*TC	ns	(3)
LVDS Clock	Input Clock to data skew	TLVCCS	-0.02*TC		0.02*TC	ns	(4)
	Spread spectrum modulation range	F <sub>clkin_mod</sub>	0.97*FC		1.03*FC	MHz	(5)
	Spread spectrum modulation frequency	F <sub>SSM</sub>			100	KHz	(5)
	Frame Rate	Fr	50	60	75	Hz	-
Vertical Display	Total	Tv	1044	1066	1450	Th	$Tv=T_{vd}+T_{vb}$
Term	Active Display	$T_{vd}$		1024		Th	-
	Blank	$T_{vb}$	20	42	426	Th	-
	Total	Th	790	844	880	Tc	$T_{h}=T_{hd}+T_{hb}$
Horizontal Display Term	Active Display	T <sub>hd</sub>		640		Tc	-
101111	Blank	T <sub>hb</sub>	150	204	240	Tc	-

Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

Note (2) The Tv(Tvd+Tvb) must be integer, otherwise, the module would operate abnormally.

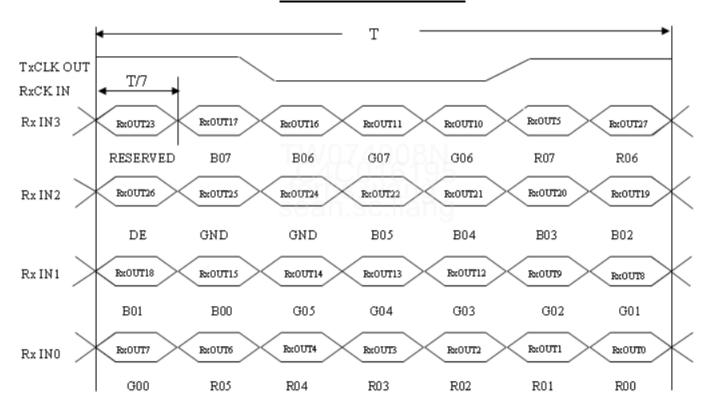
### **INPUT SIGNAL TIMING DIAGRAM**



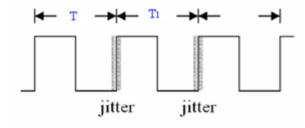
Version 2.0 10 May 2024 15 / 38



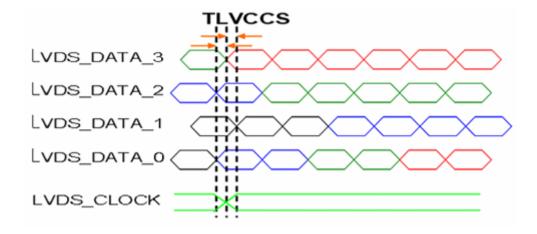
### **TIMING DIAGRAM of LVDS**



Note (3) The input clock cycle-to-cycle jitter is defined as below figures.  $T_{rcl} = I T1 - TI$ 



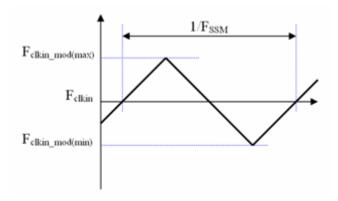
Note (4) Input Clock to data skew is defined as below figures.



Version 2.0 10 May 2024 16 / 38

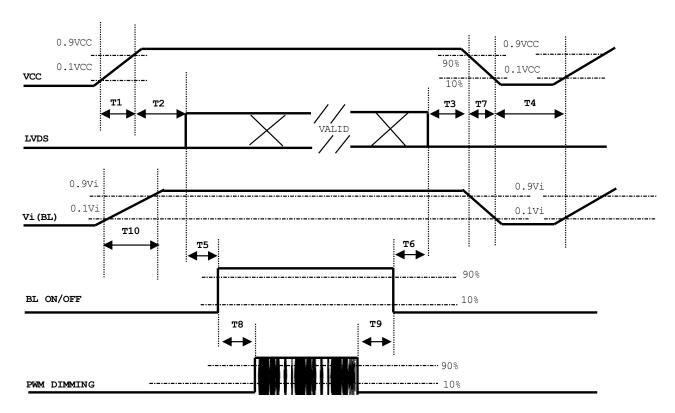


Note (5) The SSCG (Spread spectrum clock generator) is defined as below figures.



### **6.2 POWER ON/OFF SEQUENCE**

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



Version 2.0 10 May 2024 17 / 38



Doromotor		Units				
Parameter	Min	Тур	Max	Units		
T1	0.5	1	10	ms		
T2	0	-	50	ms		
T3	0	-	50	ms		
T4	500	-	-	ms		
T5	450	-	-	ms		
T6	200	-	-	ms		
Т7	10	-	100	ms		
Т8	10	-	-	ms		
Т9	10	-	-	ms		
T10	20	-	50	ms		

#### Note:

- (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.
- (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.
- (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.
- (4) T4 should be measured after the module has been fully discharged between power off and on period.
- (5) Interface signal shall not be kept at high impedance when the power is on.
- (6) INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.
- (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "T7 spec".

#### 6.3 SCANNING DIRECTION

The following figures show the image see from the front view. The arrow indicates the direction of scan.



PCBA on the top side



### 7. OPTICAL CHARACTERISTICS

### 7.1 TEST CONDITIONS

Item	Symbol	Value	Unit					
Ambient Temperature	Ta	25±2	оС					
Ambient Humidity	Ha	50±10	%RH					
Supply Voltage	Accordin	ng to typical value and tole	erance in					
Input Signal	"ELE	"ELECTRICAL CHARACTERISTICS"						
PWM Duty Ratio	D	100	%					

#### 7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown here and all items are measured at the center point of screen unless otherwise noted. The following items should be measured under the test conditions described above and stable conditions shown in Note (5).

Iter	n	Symbol	Condition	Min.	Тур.	Max.	Unit	Note	
	Bod	Rx		0.603	0.653	0.703			
	Red	Ry		0.286	3 0.653 0.703 6 0.336 0.386 3 0.323 0.373 4 0.614 0.664 1 0.151 0.201 0 0.050 0.100 3 0.313 0.363 9 0.329 0.379 0 400 (4), (6) 1 1000 - (2), (7) 1 1 16 - (3) 80 - % (5), (8) 89 -				
	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$								
Color	Green	Gy		0.564	0.614	0.664	0.703 0.386 0.373 0.664 0.201 0.100 0.363 0.379 (4), (5) (2), (5) 19 - (3) - % (5), (6) Deg. (1), (5)	(1) (5)	
Chromaticity	Pluo	Bx	$\theta X=0^{\circ}, \ \theta Y=0^{\circ}$	0.101	0.151	0.201			
	blue	Ву	By Grayscale Maximum 0.000 0.050 0.100 0.263 0.313 0.363						
White Wx 0.263 0.3	0.313	0.363							
	vviille	Wy		0.279	0.329	0.379			
Center Lumina	Center Luminance of White			320	400	-	-	(4), (5)	
Contrast	Ratio	CR		700	1000	-	-	(2), (5)	
Pospons	o Timo	TR	0V_0° 0V _0°	-	14	19	-	(2)	
Respons	e mine	TF	F θX=0°, θY =0°		11	16	-	(3)	
White Va	ariation	δW	$\theta X=0^{\circ}, \ \theta Y=0^{\circ}$	75	80	-	%	(5), (6)	
	Horizontal	θΧ+		80	89	-			
Viowing Anglo	Tionzoniai	θX-	CR>10	80	89	-	Dog	(1) (5)	
viewing Angle	Vertical	θΥ+	ON≦ IU	80	89	-	Deg.	(1), (5)	
	vertical	θΥ-		80	89	-			

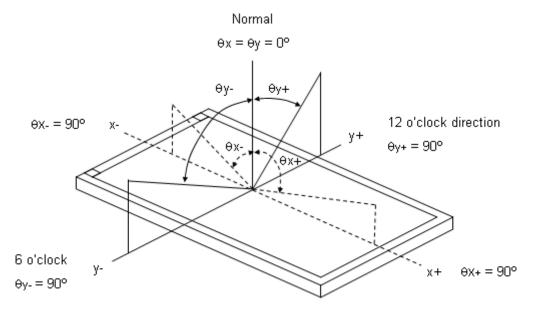
#### Definition:

Grayscale Maximum: Grayscale 255 (10 bits: grayscale 1023; 8 bits: grayscale 255; 6 bits: grayscale 63)

White: Luminance of Grayscale Maximum (All R,G,B)

Black: Luminance of grayscale 0 (All R,G,B)

Note (1)Definition of Viewing Angle ( $\theta x$ ,  $\theta y$ ):

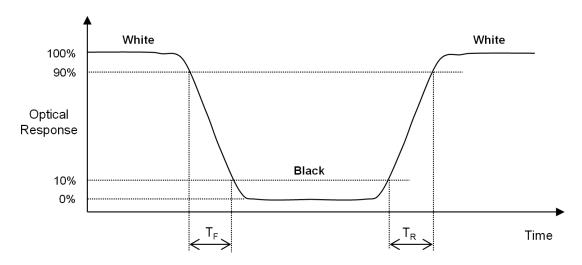


Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression at center point.

Contrast Ratio (CR) = White / Black

Note (3)Definition of Response Time (TR, TF):



Note (4) Definition of Luminance of White (L<sub>C</sub>):

Measure the luminance of White at center point.

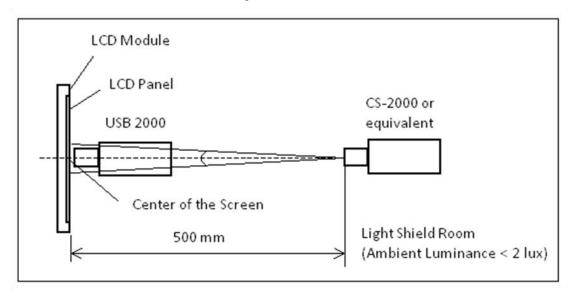
#### Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after

Version 2.0 10 May 2024 **20 / 38** 



lighting Backlight for 40 minutes in a windless room. The measurement placement of module should be in accordance with module drawing.

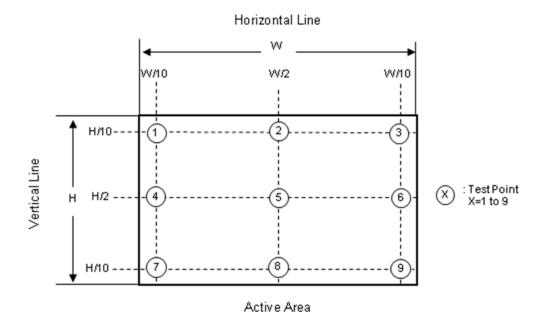


Note (6) Definition of White Variation ( $\delta W$ ):

Measure the luminance of White at 9 points.

Luminance of White: L(X), where X is from 1 to 9.

$$\delta W = \frac{\text{Minimum } [L(1) \text{ to } L(9)]}{\text{Maximum } [L(1) \text{ to } L(9)]} \times 100\%$$



Version 2.0 10 May 2024 21 / 38



### 8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note	
High Temperature Storage Test	60℃, 240 hours		
Low Temperature Storage Test	-20°C, 240 hours		
Thermal Shock Storage Test	-20°C, 0.5 hour ←→60°C, 0.5 hour; 100cycles, 1 hour/cycle)	(1) (2)	
High Temperature Operation Test	60℃, 240 hours	(1),(2) (4),(5)	
Low Temperature Operation Test	0°ℂ, 240 hours	( //( /	
High Temperature & High Humidity Operation Test	50℃, RH 80%, 240 hours		
	150pF, 330 Ω, 1 sec/cycle		
ESD Test (Operation)	Condition 1 : panel contact, ±8 KV	(1), (4)	
	Condition 2 : panel non-contact ±15 KV		
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for ± X, ± Y, ± Z direction		
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz sine wave, 10 min/cycle, 1 cycles each X, Y, Z direction	(2), (3)	

- Note (1) There should be no condensation on the surface of panel during test,
- Note (2) Temperature of panel display surface area should be 60°C Max.
- Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.
- Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.
- Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.



### 9. PACKAGING

### 9.1 PACKING SPECIFICATIONS

- (1) 11 LCD modules / 1 Box
- (2) Box dimensions: 475(L)x390(W)x410(H)mm
- (3) Weight: approximately:16.72kg (11 modules per box)

### 9.2 PACKING METHOD

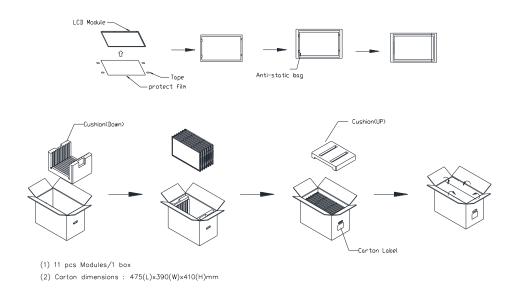


Figure. 9-1 Packing method

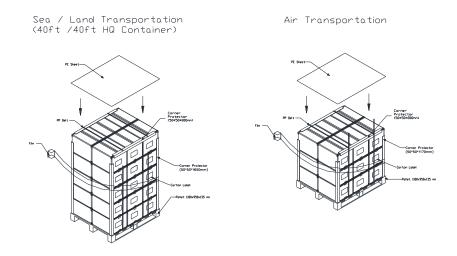


Figure. 9-2 Packing method

Version 2.0 10 May 2024 23 / 38



## 9.3 UN-PACKING METHOD

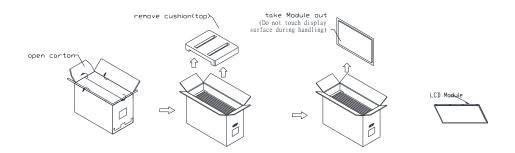


Figure. 9-3 UN-Packing method

#### 10. DEFINITION OF LABELS

#### **10.1 INX MODULE LABEL**

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.

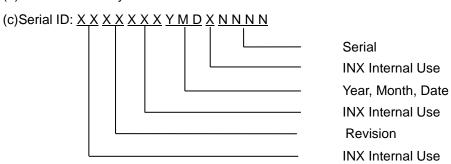




Note (1) Safety Compliance(UL logo) will open after C1 version.

(a)Model Name: G170ECE-LE2

(b)\* \* \* \* : Factory ID



Serial ID includes the information as below:

(a) Manufactured Date: Year: 1~9, for 2021~2029

Month: 1~9, A~C, for Jan. ~ Dec.

Day: 1~9, A~Y, for  $1^{st}$  to  $31^{st}$ , exclude I , O and U

(b) Revision Code: cover all the change

(c) Serial No.: Manufacturing sequence of product



#### 11 PRECAUTIONS

#### 11.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1) The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2) While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3) Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5) If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6) Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9) Do not disassemble the module.
- (10) Do not pull or fold the lamp wire.
- (11) Pins of I/F connector should not be touched directly with bare hands.

#### 11.2 STORAGE PRECAUTIONS

- (1) When storing for a long time, the following precautions are necessary.
  - (a) Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 30°C at humidity 50+-10%RH.
  - (b) The polarizer surface should not come in contact with any other object.
  - (c) It is recommended that they be stored in the container in which they were shipped.
  - (d) Storage condition is guaranteed under packing conditions.
  - (e)The phase transition of Liquid Crystal in the condition of the low or high storage temperature will be recovered when the LCD module returns to the normal condition
- (2) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (3)It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (4)It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of lamp will be higher than the room temperature.

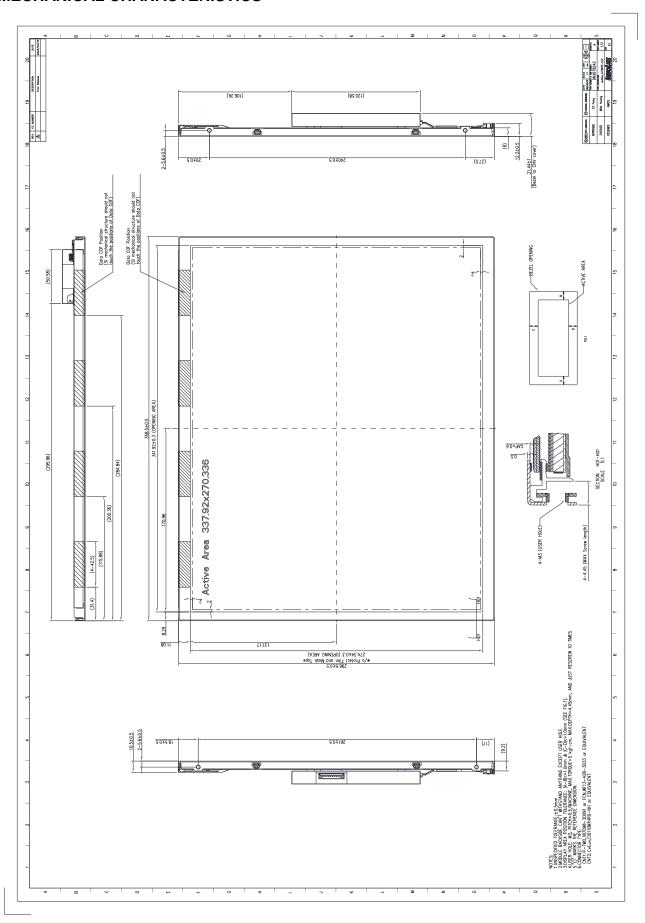


### 11.3 OTHER PRECAUTIONS

- (1) Normal operating condition
  - (a) Display pattern: dynamic pattern (Real display)(Note) Long-term static display can cause image sticking.
- (2) Operating usages to protect against image sticking due to long-term static display
  - (a) Static information display recommended to use with moving image.
- (3) Abnormal condition just means conditions except normal condition.



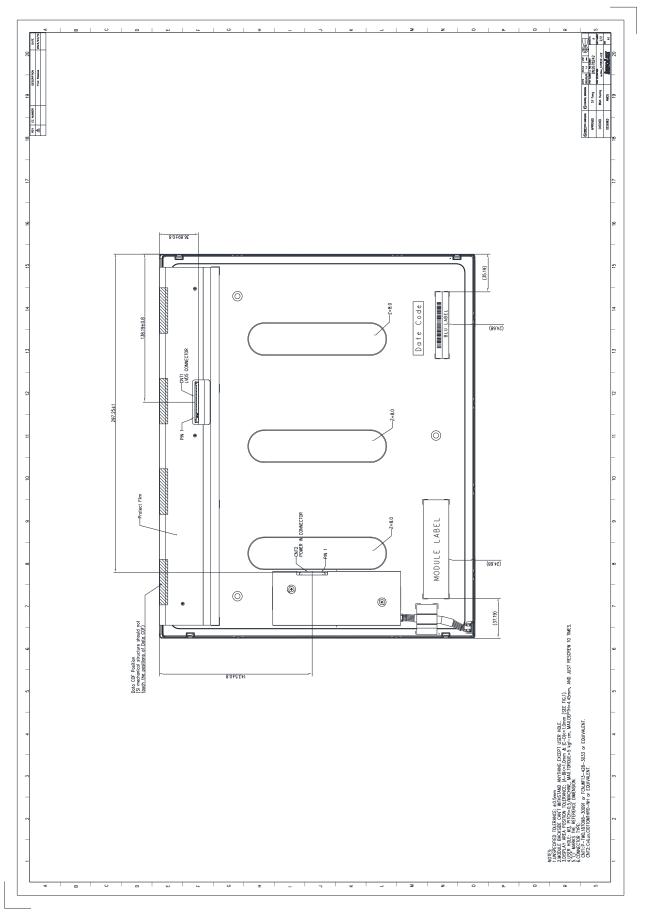
## 12. MECHANICAL CHARACTERISTICS



Version 2.0 10 May 2024 28 / 38



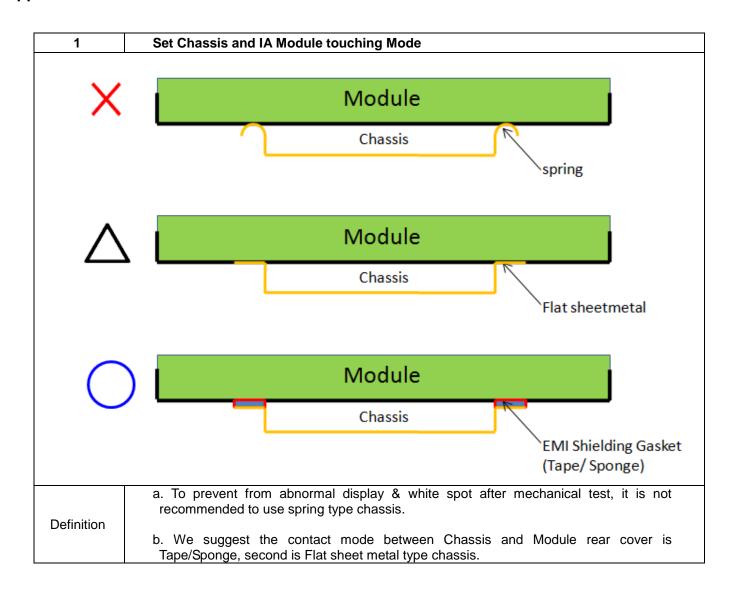




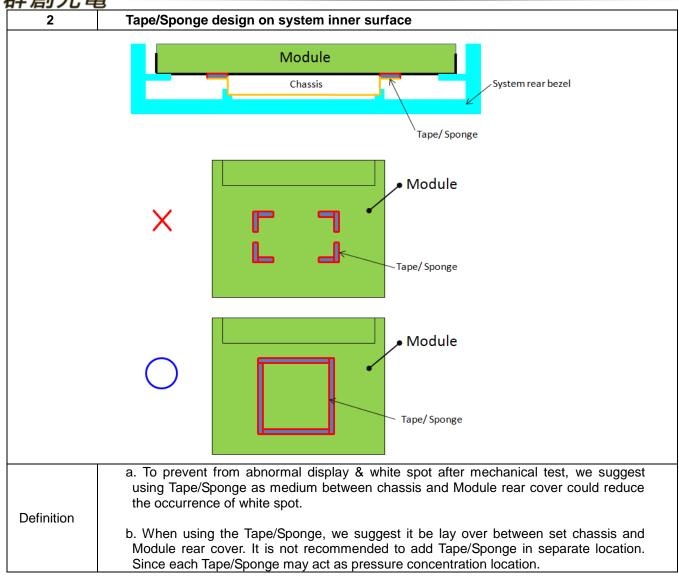
Version 2.0 10 May 2024 29 / 38



## **Appendix. SYSTEM COVER DESIGN NOTICE**

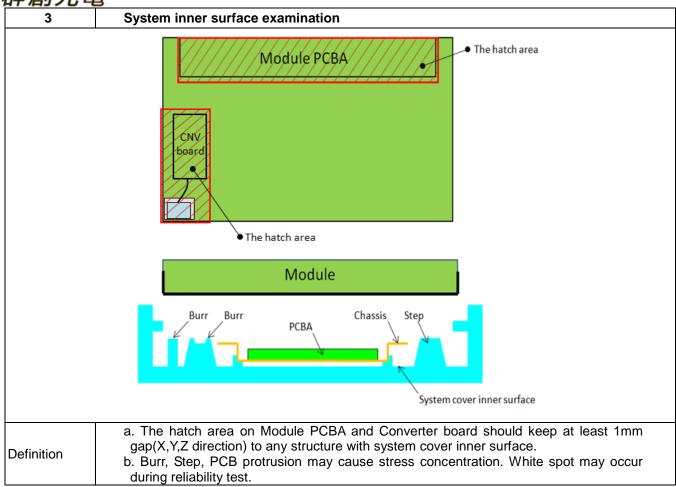


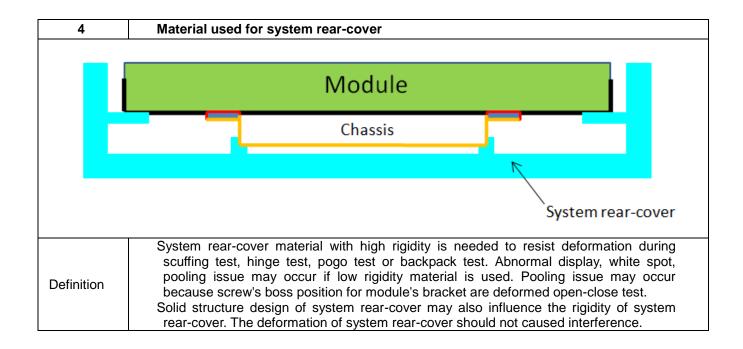




Version 2.0 10 May 2024 31 / 38

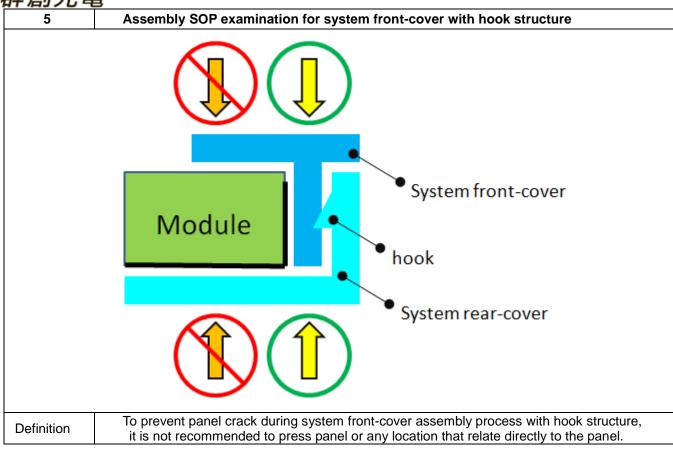






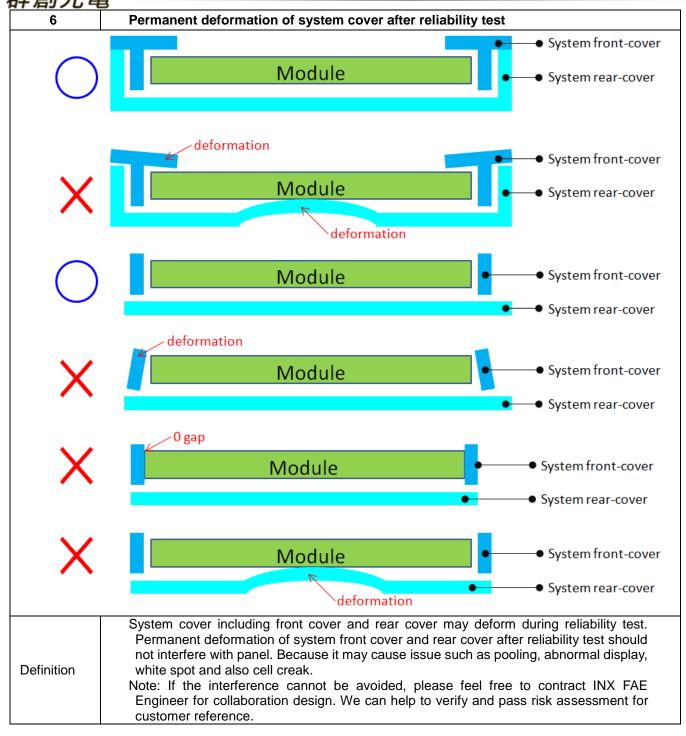
Version 2.0 10 May 2024 32 / 38





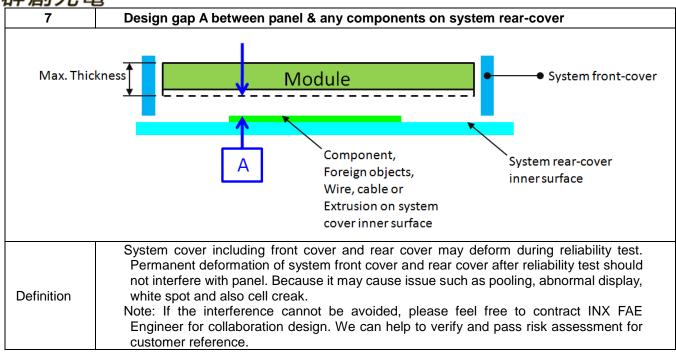
Version 2.0 10 May 2024 33 / 38

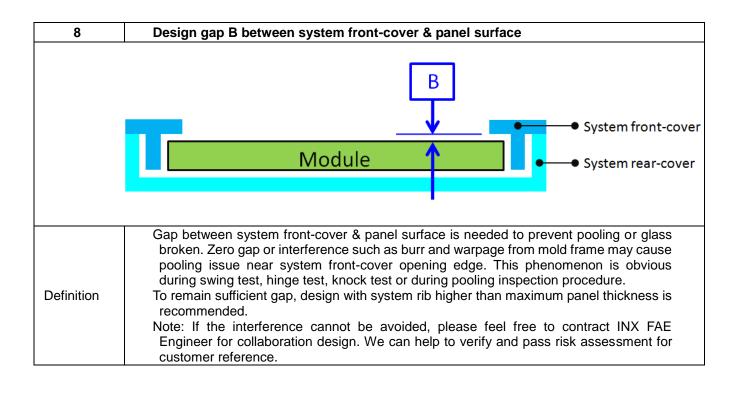




Version 2.0 10 May 2024 34 / 38

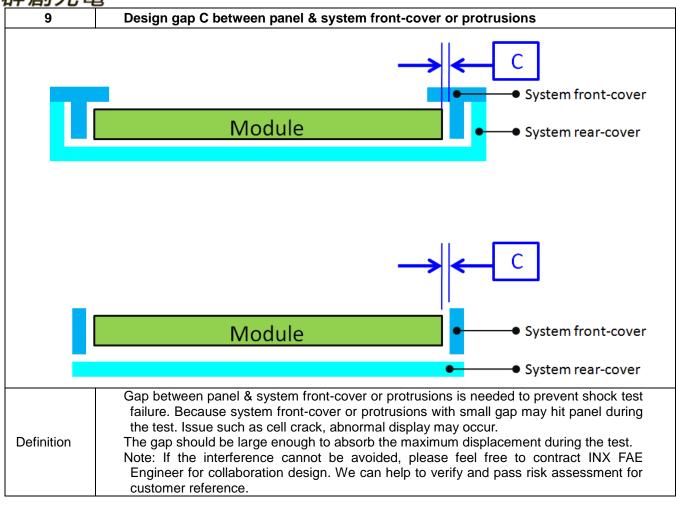






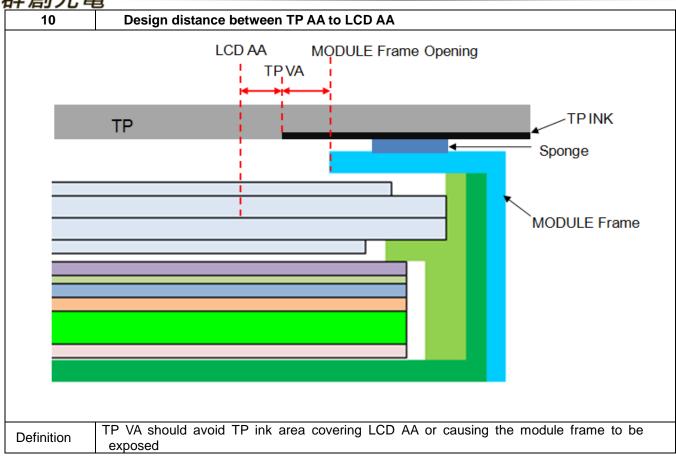
Version 2.0 10 May 2024 35 / 38





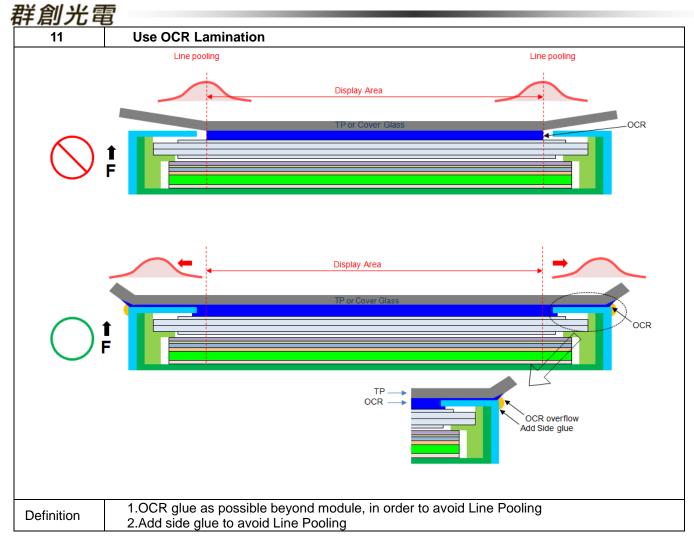
Version 2.0 10 May 2024 36 / 38





Version 2.0 10 May 2024 37 / 38





Version 2.0 10 May 2024 38 / 38